

materials letters

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Materials: Metals and alloys, amorphous solids, ceramics, composites, polymers, semiconductors.
Application: Structural, opto-electronic, magnetic, medical, MEMS, sensors, smart.
Characterization: Analytical, microscopy, scanning probes, nanoscopic, optical, electrical, magnetic, acoustic, spectroscopic, diffraction.
Novel materials: Micro and nanostructures (nanowires, nanotubes, nanoparticles), nanocomposites, thin films, superlattices, quantum dots.
Processing: Crystal growth, thin film processing, sol-gel processing, mechanical processing, assembly, nanocrystalline processing.
Properties: Mechanical, magnetic, optical, electrical, ferroelectric, thermal, interfacial, transport, thermodynamic.
Synthesis: Quenching, solid state, solidification, solution synthesis, vapor deposition, high pressure, explosive.

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